

iC-OV BLCC OVC3

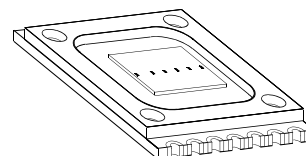
PACKAGE SPECIFICATION



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ORDERING INFORMATION

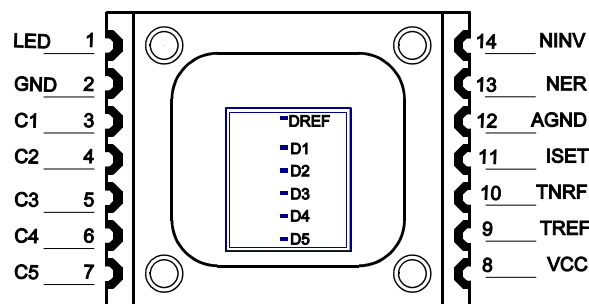
Type	Package	Options	Order Designation
iC-OV	BLCC OVC3	none	iC-OV BLCC OVC3



7.67mm x 9.15mm

PIN CONFIGURATION

(top view)



PIN FUNCTIONS

No.	Name	Function
1	LED	LED Current Control Output
2	GND	Ground
3	C1	Track1 Push-Pull Output
4	C2	Track2 Push-Pull Output
5	C3	Track3 Push-Pull Output
6	C4	Track4 Push-Pull Output
7	C5	Track5 Push-Pull Output
8	VCC	+5V Supply Voltage
9	TREF	Test Aid for Photodiode DREF
10	TNRF	Test Aid for Tracks 1 to 5 and Compensation DDC
11	ISET	LED Current Control Setup
12	AGND	Reference Ground for ISET Circuitry
13	NER	Error Message Output, low active
14	NINV	Track1 Invert Mode Input, low active

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Parameter	Conditions	Fig.				Unit
					Min.	Typ.	Max.	
TG1	Ta	Operating Ambient Temperature Range (extended temperature range on request)			-25		90	°C
TG2	Ts	Storage Temperature Range			-30		110	°C
TG3	Tl	Lead Temperature	soldering, 10 sec				230	°C

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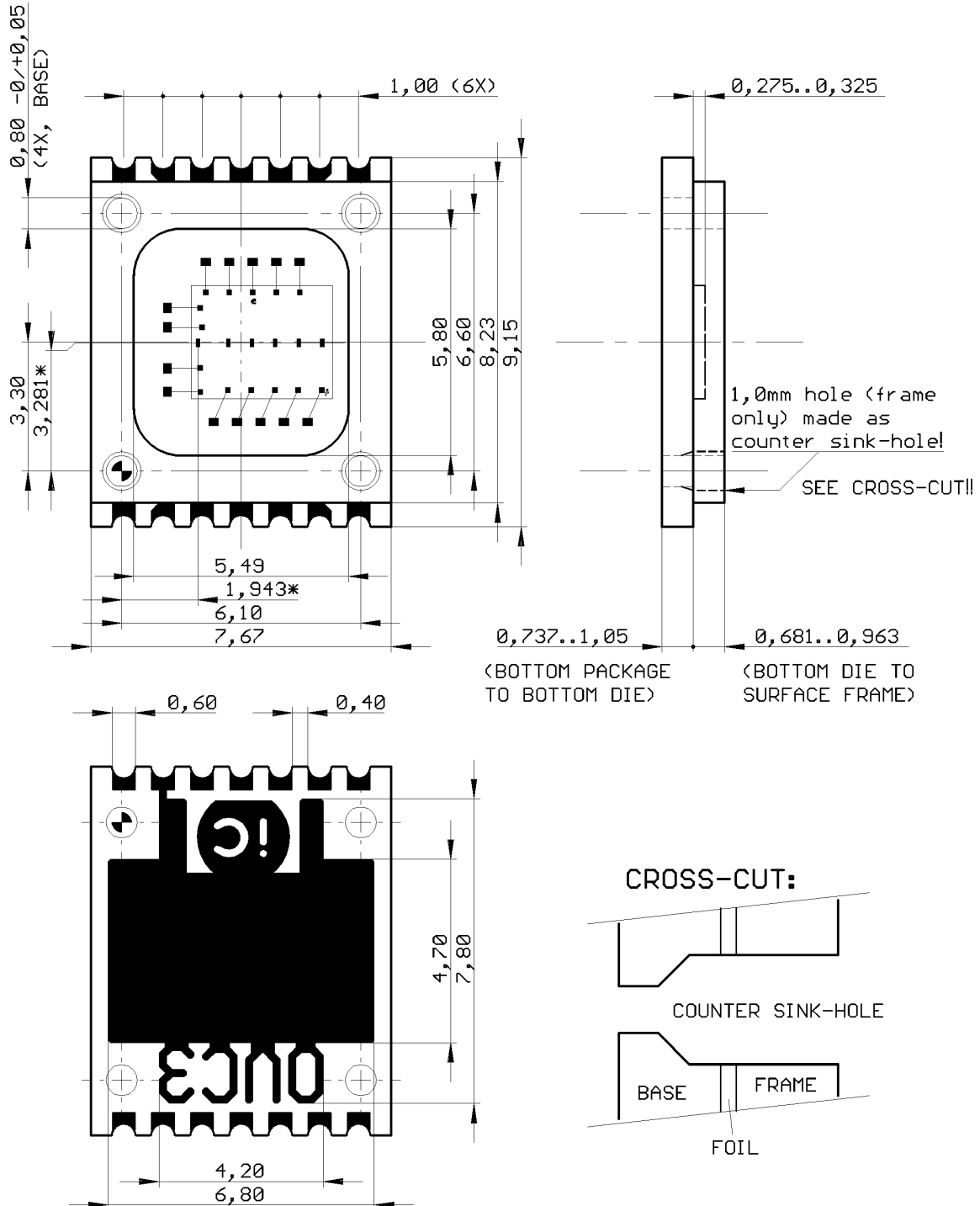
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PHYSICAL DIMENSIONS (given in mm)



- ⊕ : CENTER REFERENCE-HOLE
- * : CENTER REFERENCE-HOLE TO CENTER REFERENCE-DIODE
- HOLE TO HOLE TOLERANCE: $\pm 0,05$
- CHIP-LOCATION TOLERANCE VS. REFERENCE-HOLE: $\pm 0,10$
- CHIP-ROTATION TOLERANCE VS. PADDLE: $\pm 1,6^\circ$
- NOTE: NEGATIVE OUTLINE TOLERANCES DUE TO SINGULATION PROCESS
- ALL FRAME TOLERANCES: $\pm 200\mu\text{m}$
- COPPER-IMAGE TOLERANCES (WIDTH AND SPACING): $\pm 30\mu\text{m}$
- CENTER HOLES TO COPPER-IMAGE TOLERANCE: $\pm 75\mu\text{m}$

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REVISION HISTORY

Rev	Notes	Pages affected
A1	Initial version (iC-Haus internally)	all

GENERAL HANDLING INSTRUCTIONS

After opening the dry pack, devices must be mounted within 8 hours (in factory conditions of maximum 30 °C / 60% RH) or must be stored at <20% RH. Devices require baking before mounting if the Humidity Indicator Card shows >20% when read at 23°C ±5°C or if the conditions mentioned above are not met. Devices may be baked for 72 hours at 100°C using high-temperature device containers (trays).

Samples

Samples are not substitute for dry pack delivery and are not intended for reflow soldering. Remove any protective film if present before tempering or soldering. Use tweezers, pull upwards slowly, any horizontal pulling must be avoided. Do not touch the iC surface after removing the film. Never press on the iC coating.

This specification is for a newly developed product. iC-Haus therefore reserves the right to modify data without further notice. Please contact us to ascertain the current data. The data specified is intended solely for the purpose of product description and is not to be deemed guaranteed in a legal sense. Any claims for damage against us - regardless of the legal basis - are excluded unless we are guilty of premeditation or gross negligence.

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